

DATA SHEET

SUNGMUN CODE : NSI-21
DESCRIPTION : MINI SLIDE SWITCH

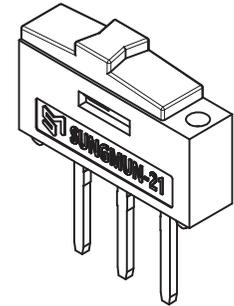
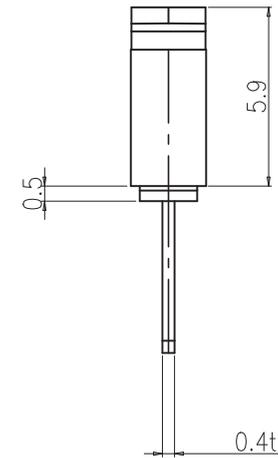
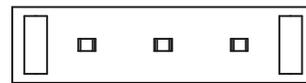
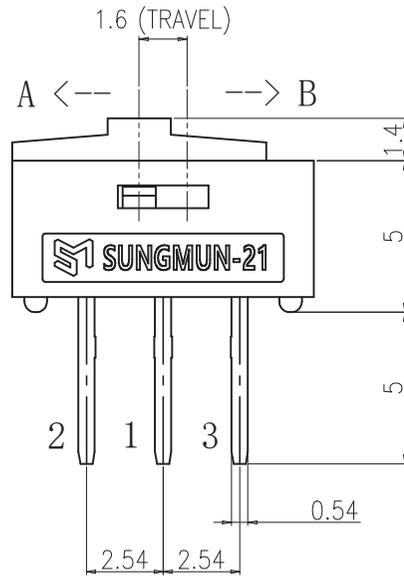
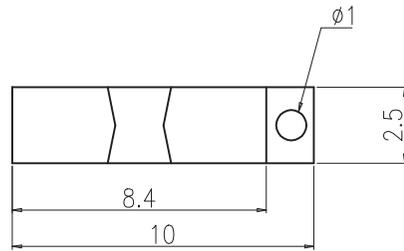
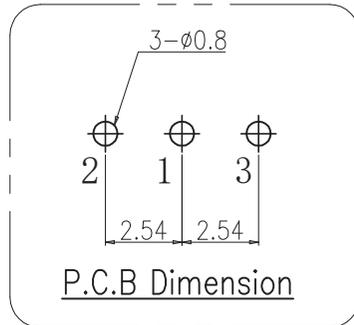
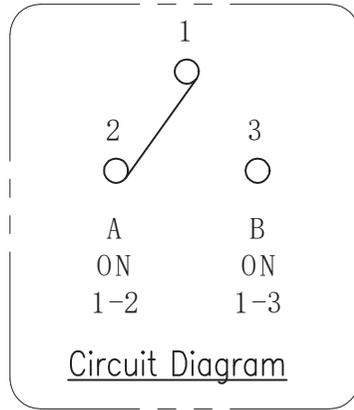
SUNGMUN ELECTRONICS CO.. LTD,

Address 301-302,Bucheon Technopark 345, Seokcheon-ro, Ojeong-gu
Bucheon-si, Gyeonggi-do, Korea
TEL. +82-32-328-1941~4
FAX +82-32-328-1945
E-mail sungmun@sungmun.co.kr
Website www.sungmun.com

REV NO.	DATE	REVISION	DR	CH	APP
△					

SPECIFICATION

1. Rating : DC12V 0.5A~24V 0.3A.
2. Contact Resistance : 80mΩ Max.
3. Travel : 1.6mm.
4. Operating Force : 250gf ± 150gf.
5. Life Cycle : 2,000 Cycle (with load).
6. Packing : 200pcs Vinyl Bag



D in ISO-2768-1m					
Ranges	0.5~3	3~6	6~30	30~120	120~400
Tolerance	±0.1	±0.1	±0.2	±0.3	±0.5

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NO.	DESCRIPTION			MATERIAL		COLOR / FINISH		REMARK	
	DRAW / DESIGNED	CHECKED	APPROVED	UNIT	G.TOL	TITLE M INISLIDE SW ITCH			
	K.N KIM	W .J LEE	K.I LEE		SCALE				
	2023-05-26	2023-05-26	2023-05-26	mm	NS	MODEL NO.	NSI-21		REV.
					SIZE	DRAW NO.	NSI-21-01		01

SUNGMUN ELECTRONICS CO.,LTD

1. Electrical Characteristics :

- 1.1 Rating : AC, DC 12V 0.5A~24V 0.3A (Minimum current: 1mA)
- 1.2 Contact Resistance : Max 30 mΩ
- 1.3 Insulation Resistance : Min 10,000 MΩ at DC 500V
- 1.4 Withstanding Voltage : 1min at AC 500V

2. Mechanical Characteristics :

- 2.1 Operating Force : 250gf ± 150gf
- 2.2 Travel : 1.6mm
- 2.3 Insulator :
 - 2.3.1 Case : Glass Fiber resin
 - 2.3.2 Slide : Glass Fiber resin
- 2.4 Terminal : Nickel, Gold Plate

3. Life Test :

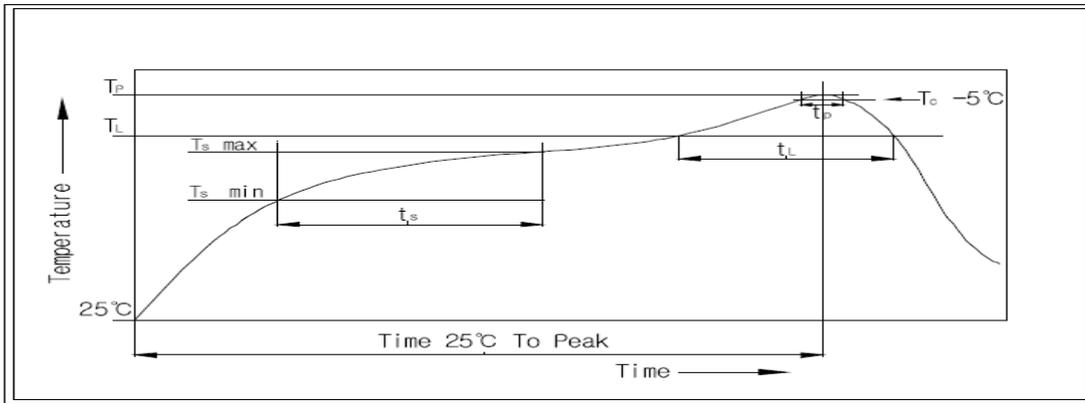
- 3.1 Test Condition : Operations at a rate of 15-20 cycles in 1 minute
 - 3.1.1 With load : 2,000 cycles
 - 3.1.2 Without load : 10,000 cycles
- 3.2 Operating Force : With +40%, -40% of Initial Value
- 3.3 Contact Resistance : Max 200mΩ

4. Environmental Characteristics :

- 4.1 Operating Temperature : -40°C to +85°C
- 4.2 Storage Temperature : -40°C to +85°C
- 4.3 Humidity Test :
 - 4.3.1 Test Conditions : Measured 1hour after exposure to ambient
After 96hours exposure at 40±2°C, 90-95% R.H
 - 4.3.2 Insulation Resistance : Min 100MΩ, at DC 500V
 - 4.3.3 Withstanding Voltage : 1min at AC 250V

5. Solder Conditions :

- 5.1 Hand Solder : 3~4 sec. at 350°C (Dipping type)
- 5.2 Wave Solder : 5 sec. at 260°C (Dipping type)
- 5.3 Reflow Solder (SMD type)



5.3.1 Condition for Soldering

Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate(Ts max to TP)	3°C/second max
Preheat	
- Temperature Min(Ts min)	150°C
- Temperature Max(Ts max)	200°C
- Time (ts min to ts max)	60-180seconds
Time maintained above:	
- Temperature (TL)	217°C
- Time (tL)	60-150seconds
Peak/Classification Temperature(TP)	260°C +0°C/ -5°C
Time within 5°C of actual Peak Temperature(TP)	5~10 seconds
Ramp-Down Rate	6°C/sec max
Time 25°C to Peak Temperature	8 minutes max